

METHOD FOR PREVENTING VOID FORMATION IN A SOLDER JOINT

ABSTRACT

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In one disclosed embodiment, the present method for preventing void formation in a solder joint formed between two metallic surfaces includes forming (410) at least one slit (218) in a layer of solder to form a slit solder layer (214), positioning (440) the slit solder layer between the two metallic surfaces, and heating (450) the slit solder layer to
10 form the solder joint, wherein the at least one slit forms an outgas alley to prevent void formation in the solder joint. Where solder joint width is a concern, the present method includes applying (450) external pressure concurrently with heating (450). The outgas alley is formed to provide a ready avenue of escape for flux gasses produced during formation of the solder joint.

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Figure 4